/ Descriptions

Schottky Barrier Diode in a TO-263 Plastic Package.

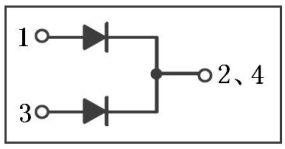
/ Features

Low forward voltage drop,low power losses,High efficiency operation.

/ Applications

For use in high frequency inverters, switching power supplies, freewheeling diodes,OR-ing diode, dc-to-dc converters and reverse battery protection.

/ Equivalent Circuit



/ Pinning

PIN1 Anode PIN 2 4 Cathode PIN 3 Anode

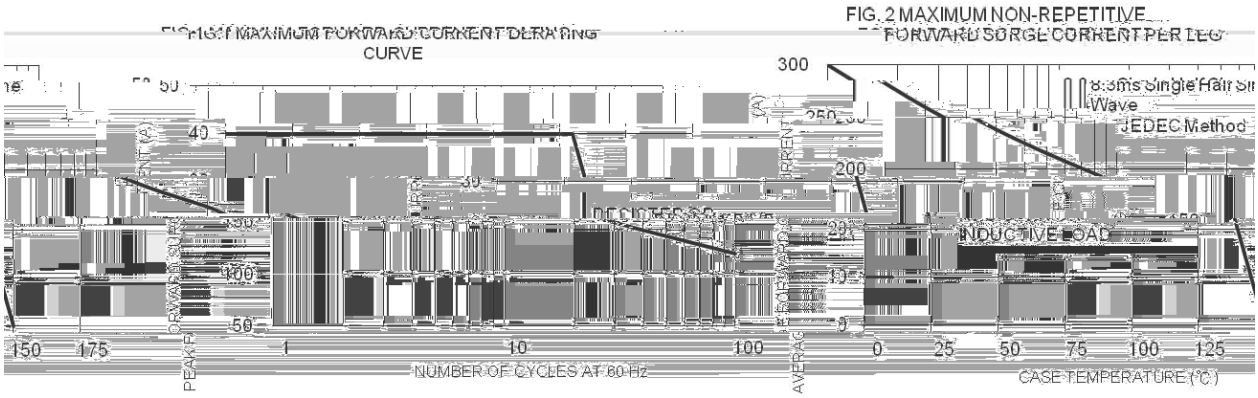
/ h_{FE} Classifications & Marking

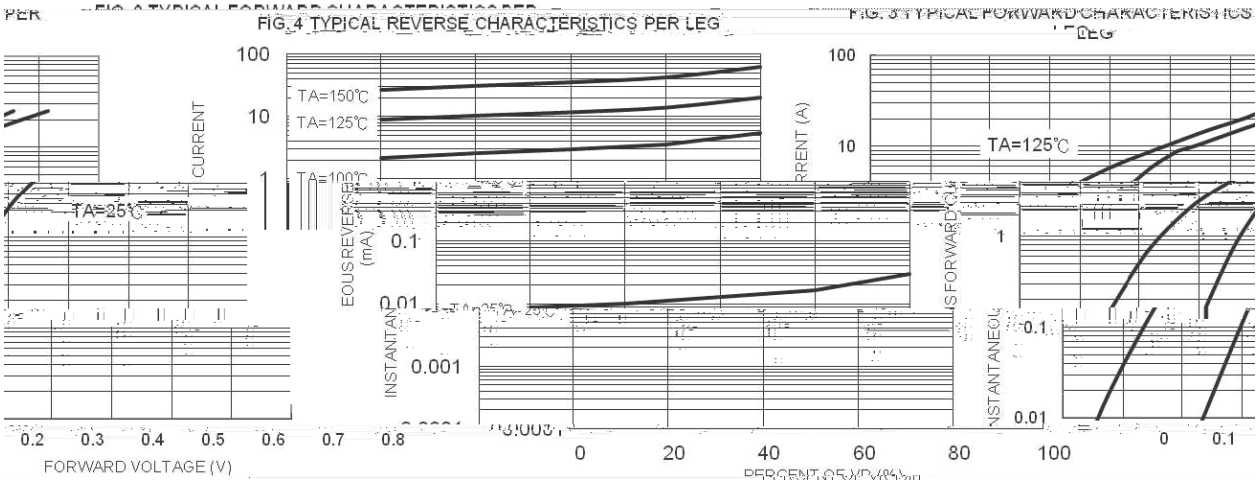
See Marking Instructions.

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RM} V_{RSM} V_{DC}	100	V
RMS Reverse Voltage	V_{RMS}	70	V
Average Rectified Forward Current	$I_{F(AV)}$	2×20	A
Non Repetitive Peak Surge Current	I_{FSM}	300	A
Thermal Resistance Junction to Case	$R_{\theta Jc}$	1.8	/W
Junction and Storage Temperature Range	T_j T_{stg}	-40 +150	

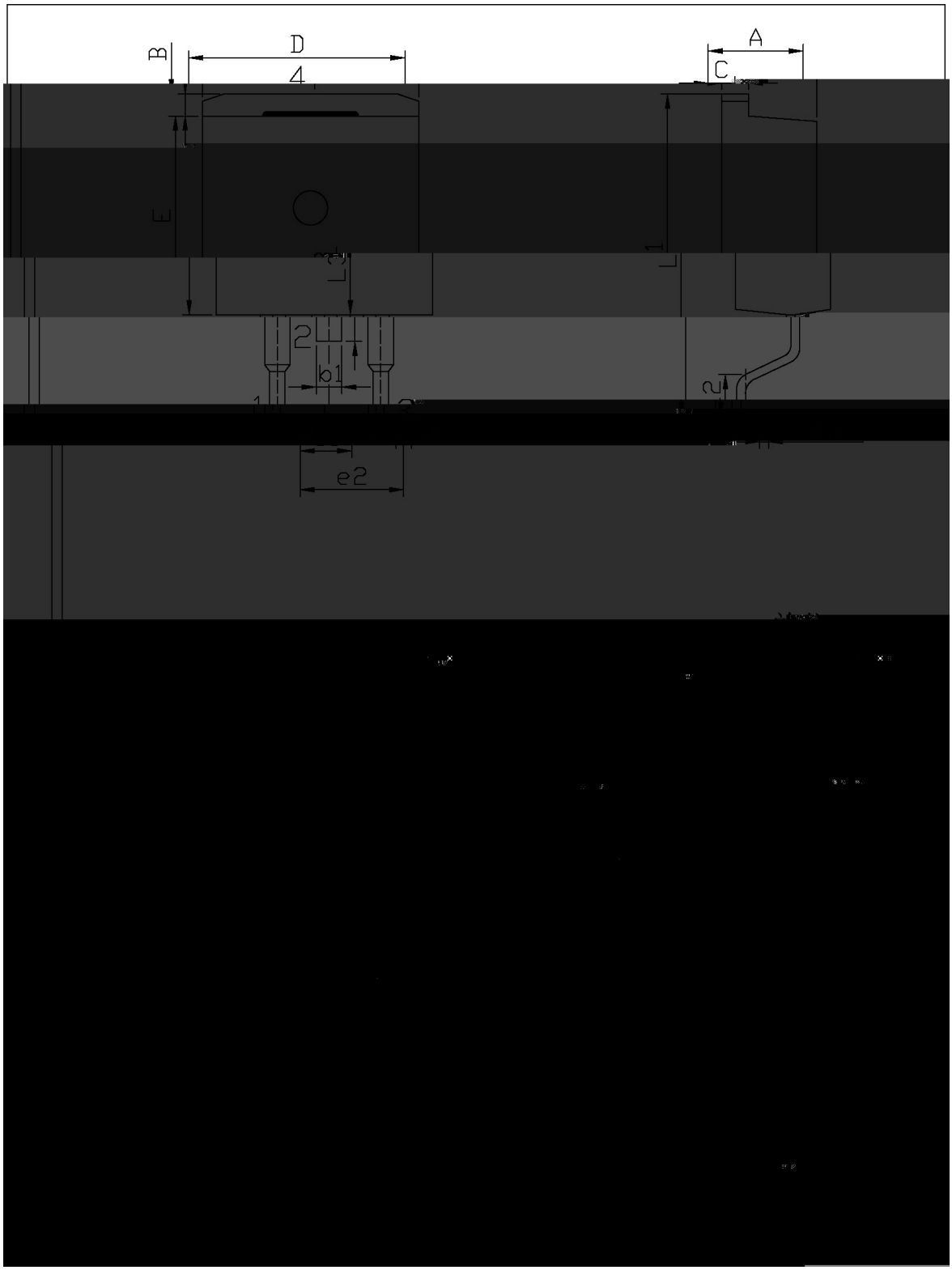
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	V_{BR}	I_R=1mA(Ta=25)	100			V
Forward Voltage	V_F	I_F =5A(Ta=25)		0.45		V
		I_F =10A(Ta=25)		0.54		V
		I_F =20A(Ta=25)		0.67	0.75	V
		I_F =5A(Ta=125)		0.38		V

/ Electrical Characteristic Curve

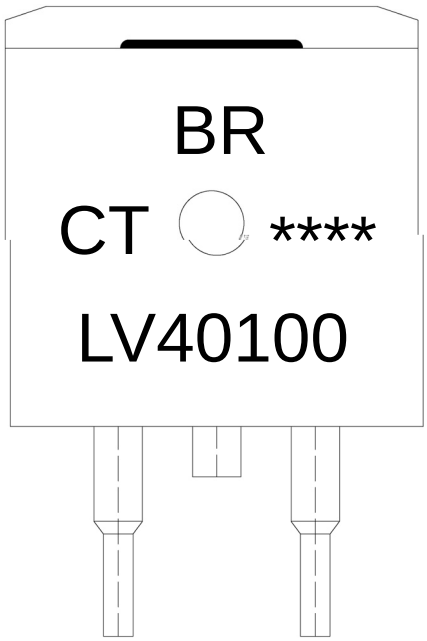




/ Package Dimensions



/ Marking Instructions

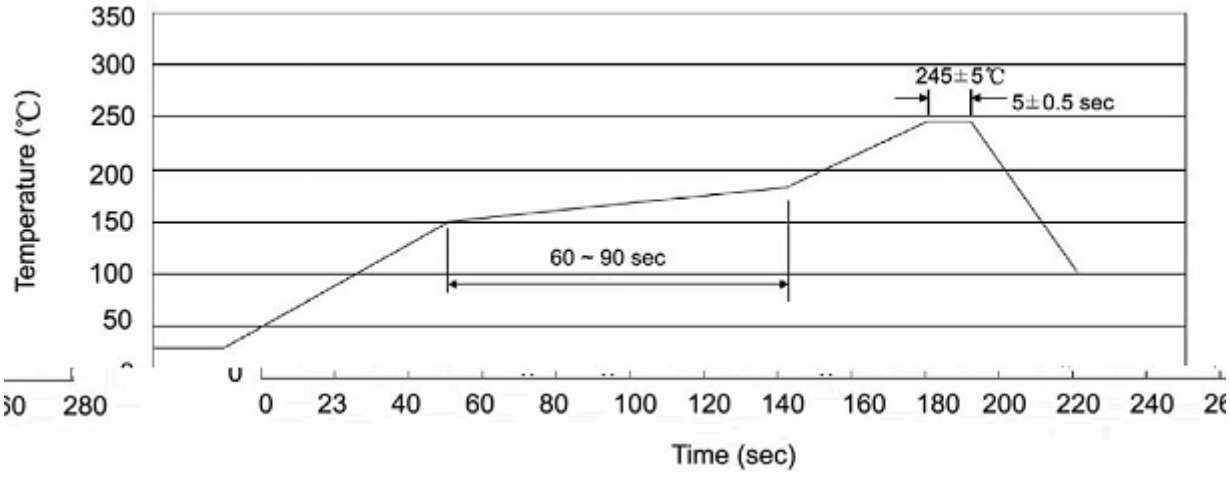


BR

Note:

BR:	Company Code
	Product Type.
:	Internal Structure
****:	Lot No. Code, code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



Note:

1	25	150	60	90sec;	1.Preheating:25~150 , Time:60~90sec.
2	245	5	5	0.5sec;	2.Peak Temp.:245 5 , Duration:5 0.5sec.
3		2 10 /sec.			3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5	10 1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm³)		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱

/ TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm³)		
	只 套管	套管 盒	只 盒	盒 箱	只 箱	套管	盒	箱

/ Notices